MILITARY INFORMATION

DISTINCTIVE CHARACTERISTICS

- 2 and 3 MHz operation; fixed point 16-bit and 32-bit operations
- Floating point 32-bit operations; binary data formats
- Add, Subtract, Multiply and Divide; trigonometric and inverse trigonometric functions
- Square roots, logarithms, exponentiation; float-to-fixed fixed-to-float conversions
- Stack-oriented operand storage; DMA or programmed I/O data transfers
- End signal simplifies concurrent processing; Synchronous/Asynchronous operations
- General purpose 8-bit data bus interface; standard 24pin package

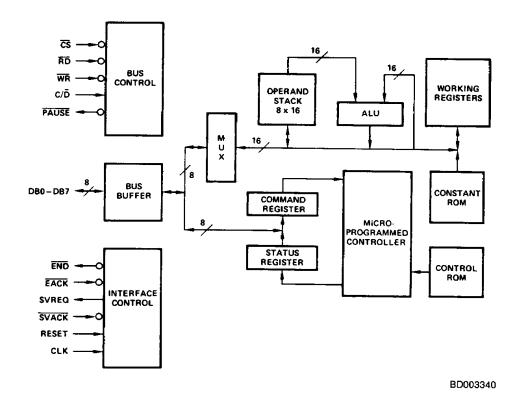
GENERAL DESCRIPTION

The Am9511A Arithmetic Processing Unit (APU) is a monolithic MOS/LSI device that provides high-performance fixed and floating point arithmetic and a variety of floating point trigonometric and mathematical operations. It may be used to enhance the computational capability of a wide variety of processor-oriented systems.

All transfers, including operand, result, status, and command information, take place over an 8-bit bidirectional data bus. Operands are pushed onto an internal stack, and a command is issued to perform operations on the data in the stack. Results are then available to be retrieved from the stack, or additional commands may be entered.

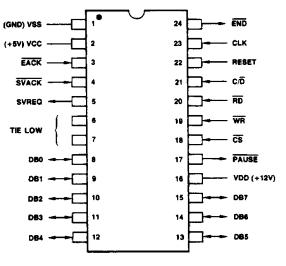
Transfers to and from the APU may be handled by the associated processor using conventional programmed I/O, or may be handled by a direct memory access controller for improved performance. Upon completion of each command, the APU issues an end-of-execution signal that may be used as an interrupt by the CPU to help coordinate program execution.

BLOCK DIAGRAM



Publication # Rev. <u>Amendment</u> 09224 Issue Date: December

CONNECTION DIAGRAM Top View



CD005172

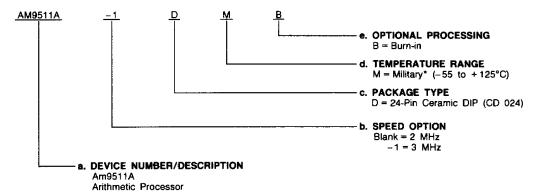
Note: Pin 1 is marked for orientation.

MILITARY ORDERING INFORMATION

NPL Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option (if applicable)
- c. Package Type
- d. Temperature Range
- e. Optional Processing



Valid	Com	binations
AM9511A		DMB
AM9511A-1		

*Military or Limited Military temperature range products are "NPL" (Non-Compliant Products List) or Non-MIL-STD-883C Compliant products only.

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released combinations, and to obtain additional data on AMD's standard military grade products.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature65	to +150°C
V _{DD} with Respect to V _{SS} 0.5 V t	
V _{CC} with Respect to V _{SS} 0.5 V	to +7.0 V
All Signal Voltages	
with Respect to VSS5.0 V	to +7.0 V
Power Dissipation (Package Limitation)	

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Military (M) Devices			
Temperature (T _C)	to	+	125°C
Supply Voltage (V _{CC})	5	٧	±10%
(V _{DD})1	2	٧	±10%

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range

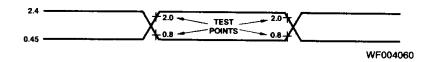
Parameter Symbol	Parameter Description	Test Conditions Min.		Max.	Unit
VOH Output HIGH Voltage		I _{OH} = -200 μA	3.7		
V _{OL}	Output LOW Voltage	I _{OL} = 3.2 mA	<u> </u>	0.4	i v
VIH	Input HIGH Voltage		2014	Ycc⁺	V
V _{IL}	Input LOW Voltage		TO THE SERVICE	0.8	- ·
llχ	Input Load Current	V _{SS} ≤ VI ≤ V _{CC}		±10	μΑ
loz	Data Bus Leakage	V _O = 0.4 V	10		μА
		¥0 = 1		10	μας
lcc	V _{CC} Supply Current			100	mA

CAPACITANCE A MAIN

Parameter Symbol	Prage r Description	Test Conditions	Min.	Max.	Unit
Co	Output Capacitance	f _C = 1.0 MHz, Inputs = 0 V		10*	ρF
CI	Input Capacitance			8*	ρF
C _{IO}	I/O Capacitance			12*	pF

^{*}Not tested; guaranteed by design.

SWITCHING TEST INPUT WAVEFORM



SWITCHING CHARACTERISTICS over operating range

Parameter			Am9511A		Am9511A-1		
Symbol			Min.	Max.	Min.	Max.	Unit
TAPW	EACK LOW Pulse Width		100		75	<u> </u>	ns
TCDR	C/D to RD LOW Setup Time	•	0		ō		ns
TCDW	C/D to WR LOW Setup Time		0		0		ns
TCPH	Clock Pulse HIGH Width		200		140		ns
TCPL	Clock Pulse LOW Width		240	~	160		ns
TCSR	CS LOW to RD LOW Setup Time		0		0		ns
TCSW	CS LOW to WR LOW Setup Time		0		0	 	ns
TCY	Clock Period		480	5000	320	3300	ns
TDW	Data Bus Stable to WR HIGH Setup Time		150		150	7	ns
TEAE	EACK LOW to END HIGH Delay			20		175	ns
TEPW	END LOW Pulse Width (Note 4)		400	4 To 10	270		ns
TOP	Data Bus Output Valid to PAUSE HIGH Delay	·, ·	0,	18	0		ns
T0014/D	PAUSE LOW Pulse Width Read (Note 5)	Data	3.5TCY 50	5.5TCY + 300	3.5TCY + 50	5.5TCY + 200	ns
TPPWR		Status	5TCT TO	3.5TCY + 300	1.5TCY + 50	3.5TCY + 200	
TPPWW	PAUSE LOW Pulse Width Write (Note 8)	4	7	50		50	ns
TPR	PAUSE HIGH to RD HIGH Hold Time	10	0		0		ns
TPW	PAUSE HIGH to WR HIGH Hold Time	A 1	0		O		ns
TRCD	RD HIGH to C/D Hold Time		0		0		ns
TRCS	RD HIGH to CS HIGH Hole Time	. •	0		0		ns
TRO	RD LOW to Data II ON Death		50		50		ns
TRP	RD LOW to PASE Delay (Note 6)			150		150	ns
TRZ	RD HIGH to Data to S OFF Delay		50	200	50	150	ns
TSAPW	SVACK LOW Pulse Width		100		75		ns
TSAR	SVACK LOW to SVREQ LOW Delay			300		200	ns
TWCD	WR HIGH to C/D Hold Time		60		30		ns
TWCS	WR HIGH to CS HIGH Hold Time		60		30		ns
TWD	WR HIGH to Data Bus Hold Time		20	1	20		ns
		Command	4TCY	1	4TCY		ns
TWI	Write Inactive Time	Data	5TCY		5TCY		
TWP	WR LOW to PAUSE LOW Delay (Note 6)			150	· · · · · · · · · · · · · · · · · · ·	150	ns

Notes: 1. Typical values are for T_A = 25°C, nominal supply voltages and nominal processing parameters.

2. Switching parameters are listed in alphabetical order.

3. Test conditions assume transition times of 20 ns or less, output loading of one TTL gate plus 100 pF ±20 pF and timing reference

 Test conditions assume transition times of 20 ns or less, output loading or one LIL gate plus 100 pr ±20 pr and uning relevance levels of 0.8 V and 2.0 V.
 END low pulse width is specified for EACK tied to VSS. Otherwise TEAE applies.
 Minimum values shown assume no previously entered command is being executed for the data access. If a previously entered command is being executed, PAUSE LOW Pulse Width is the time to complete execution plus the time shown. Status may be read at any time without exceeding the time shown.
 PAUSE is pulled low for both command and data operations.
 TEX is the execution time of the current command (see the Command Execution Times table).
 PAUSE low pulse width is less than 50 ns when writing into the data port or the control port as long as the duty requirement (TWI) is observed and no previous command is being executed. TWI may be safely violated up to 500 ns as long as the extended TPPWW that results is observed. If a previously entered command is being executed, PAUSE LOW Pulse Width is the time to complete execution plus the time shown. complete execution plus the time shown.

CHAPTER 6



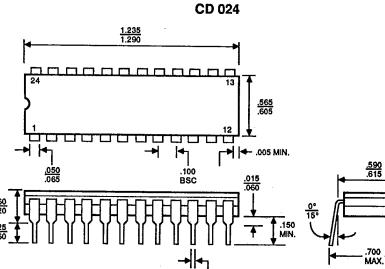
General Information

T-90-20

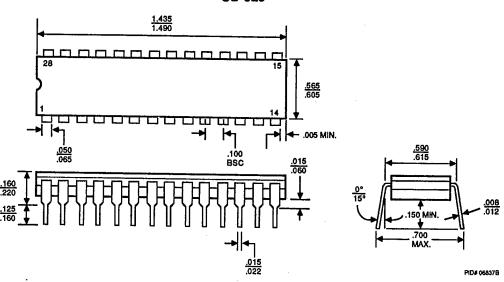
PID# 07156B

PACKAGE OUTLINES*

Ceramic DIPs (CD)



CD 028



* For reference only.

NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

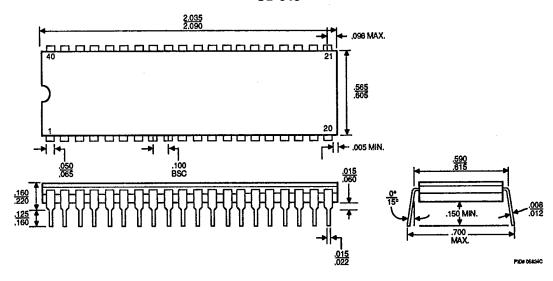
6-1

1780

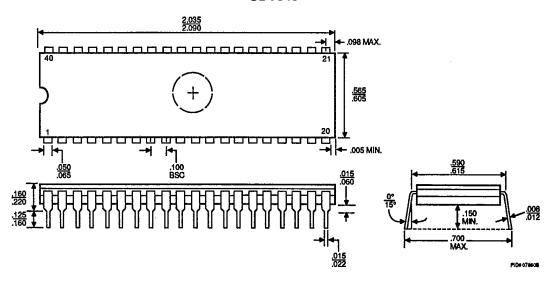
A-11

PACKAGE OUTLINES (Continued)

Ceramic DIPs (CD) (Continued) CD 040



CDV040



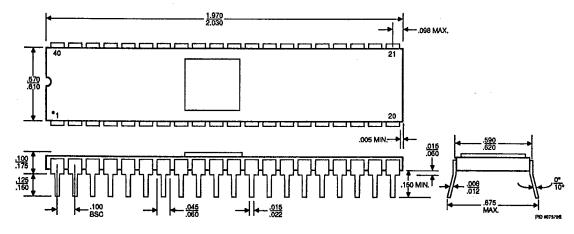
NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

CHAPTER 6 General Information

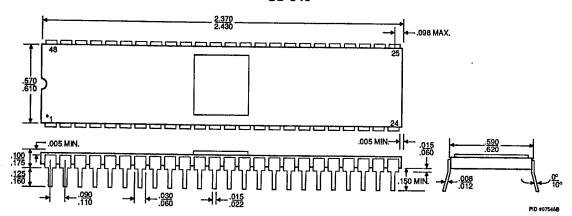
PACKAGE OUTLINES (Continued)

T-90-20

Ceramic Sidebrazed DIPs (SD) SD 040



SD 048



NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

6-3

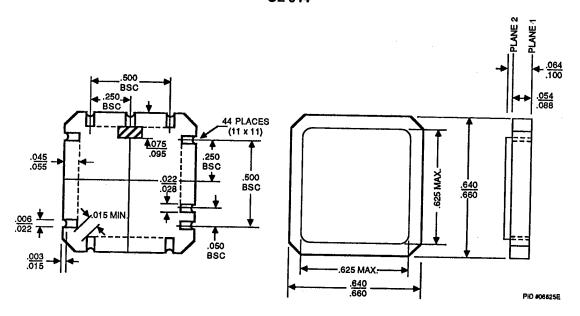
1782

CHAPTER 6
General Information

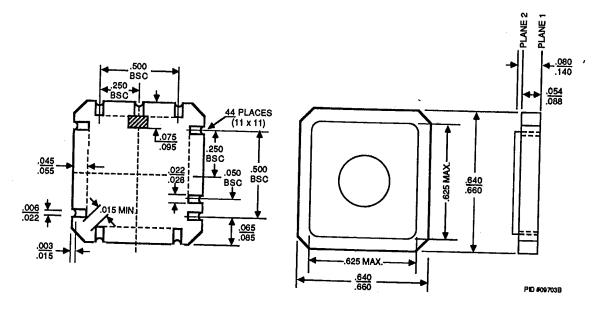
T-90-20

PACKAGE OUTLINES (Continued)

Ceramic Leadless Chip Carriers (CL/CLV) CL 044



CLV044



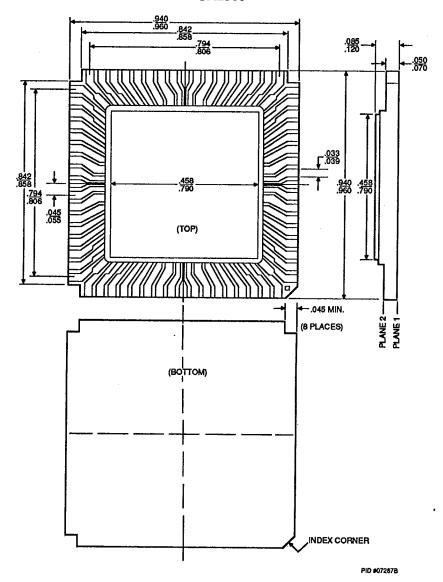
NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

T-90-20

CHAPTER 6
General Information

PACKAGE OUTLINES (Continued)

68-Pin Square Leadless Chip Carrier (CA2) CA2068



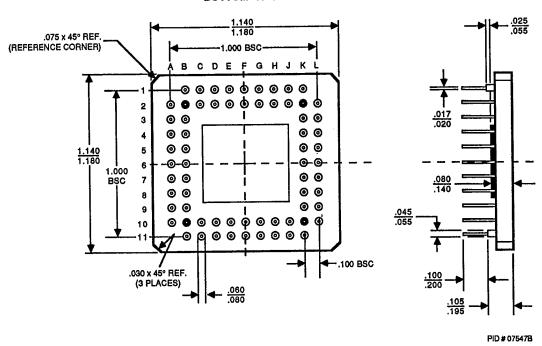
NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

1784 B-01

PACKAGE OUTLINES (Continued)

Ceramic Pin-Grid-Array Package (CG/CGX) CGX068

BOTTOM VIEW



NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.